

Amendments to the Claims:

Please amend claims 51-56, cancel claim 50, and add new claims 84 and 85. Following is a complete listing of the claims pending in the application, as amended:

1-50. (Cancelled)

51. (Currently amended) The assembly of claim ~~50~~53, further comprising a conductive connecting member connected directly between the second packaged microelectronic device and the support member circuitry, at least a portion of the connecting member being positioned adjacent to an outer edge of the first packaged microelectronic device.

52. (Currently amended) ~~The assembly of claim 50~~ An assembly of packaged microelectronic devices, comprising:

a support member having support member circuitry;

a first packaged microelectronic device connected to at least one of the support member and the support member circuitry and having a first microelectronic die generally encased in a first encapsulant to define a first package configuration; and

a second packaged microelectronic device connected to at least one of the support member and the support member circuitry with the first packaged microelectronic device positioned between the support member and the second packaged microelectronic device, the second packaged microelectronic device having a second microelectronic die generally encased in a second encapsulant to define a second package configuration different than the first package configuration, and wherein the second packaged microelectronic device is not fixedly attached to the first packaged microelectronic device,

wherein the first packaged microelectronic device has a first edge and a second edge facing opposite the first edge and the second packaged microelectronic device has a third edge and a fourth edge facing opposite the third edge, and wherein the third edge of the second packaged microelectronic device extends outwardly beyond the first edge of the first packaged microelectronic device and the fourth edge of

the second packaged microelectronic device extends outwardly beyond the second edge of the first packaged microelectronic device.

53. (Currently amended) ~~The assembly of claim 50~~ An assembly of packaged microelectronic devices, comprising:

a support member having support member circuitry;

a first packaged microelectronic device connected to at least one of the support member and the support member circuitry and having a first microelectronic die generally encased in a first encapsulant to define a first package configuration; and

a second packaged microelectronic device connected to at least one of the support member and the support member circuitry with the first packaged microelectronic device positioned between the support member and the second packaged microelectronic device, the second packaged microelectronic device having a second microelectronic die generally encased in a second encapsulant to define a second package configuration different than the first package configuration, and wherein the second packaged microelectronic device is not fixedly attached to the first packaged microelectronic device,

wherein the first packaged microelectronic device has a first planform shape in a plane generally parallel to a plane of the support member and the second packaged microelectronic device has a second planform shape in a plane generally parallel to the plane of the support member, and further wherein the second planform shape is more extensive in at least one direction generally parallel to the plane of the support member than is the first planform shape.

54. (Currently amended) The assembly of claim ~~50~~53, wherein the second packaged microelectronic device is spaced apart from the first packaged microelectronic device to define a gap between the packaged devices.

55. (Currently amended) The assembly of claim ~~50~~53 wherein the second packaged microelectronic device has a plurality of conductive members electrically coupled to the second microelectronic die and extending away from the second encapsulant, further wherein all the

conductive members extending away from the second encapsulant are attached directly between the second packaged microelectronic device and the support member circuitry without being attached to the first packaged microelectronic device.

56. (Withdrawn—Currently amended) The assembly of claim ~~50~~53, further comprising solder balls connected to the second packaged microelectronic device and the support member, the solder balls being positioned at least proximate to an outer edge of the first packaged microelectronic device.

57. (Previously presented) An assembly of packaged microelectronic devices, comprising:

- a support member;

- a first packaged microelectronic device connected to the support member and having a first microelectronic die generally encased in a first encapsulant to define a first planform shape; and

- a second packaged microelectronic device connected to the support member with the first packaged microelectronic device positioned between the support member and the second packaged microelectronic device, the second packaged microelectronic device having a second microelectronic die generally encased in a second encapsulant to define a second planform shape different than the first planform shape.

58. (Original) The assembly of claim 57 wherein the support member defines a support member plane and the first planform shape describes an area in a first plane generally parallel to the support member plane that is smaller than an area described by the second planform shape in a second plane generally parallel to the support member plane.

59. (Original) The assembly of claim 57, further comprising a conductive connecting member connected directly between the second packaged microelectronic device and the support

member circuitry, at least a portion of the connecting member being positioned adjacent to the first packaged microelectronic device.

60. (Original) The assembly of claim 57 wherein the first packaged microelectronic device has a first edge and a second edge facing opposite the first edge and the second packaged microelectronic device has a third edge and a fourth edge facing opposite the third edge, and wherein the third edge of the second packaged microelectronic device extends outwardly beyond the first edge of the first packaged microelectronic device and the fourth edge of the second packaged microelectronic device extends outwardly beyond the second edge of the first packaged microelectronic device.

61. (Original) The assembly of claim 57 wherein the second packaged microelectronic device is spaced apart from the first packaged microelectronic device to define a gap between the packaged devices.

62. (Original) The assembly of claim 57 wherein the second packaged microelectronic device has a plurality of conductive members electrically coupled to the microelectronic substrate and extending away from the second encapsulant, further wherein all the conductive members extending away from the second encapsulant are attached directly between the second packaged microelectronic device and the support member circuitry.

63. (Cancelled)

64. (Previously presented) The assembly of claim 65 wherein the first packaged microelectronic device includes a first surface facing toward the support member, a second surface facing away from the support member and toward the second packaged microelectronic device, and a plurality of third surfaces between the first and second surfaces, further wherein the elongated connection members are positioned adjacent to the third surfaces of the first packaged microelectronic device.

65. (Previously presented) An assembly of packaged microelectronic devices, comprising:

a support member;

a first packaged microelectronic device having a first microelectronic die generally encased in a first encapsulant and connected to the support member with a plurality of solder balls, the first packaged microelectronic device having a first edge and a second edge facing opposite the first edge; and

a second packaged microelectronic device having a second microelectronic die generally encased in a second encapsulant and connected to the support member with a plurality of elongated connection members extending from the second packaged microelectronic device around at least part of the first packaged microelectronic device and attached directly to the support member, the second packaged microelectronic device having a third edge and a fourth edge facing opposite the third edge, and wherein the third edge of the second packaged microelectronic device extends outwardly beyond the first edge of the first packaged microelectronic device and the fourth edge of the second packaged microelectronic device extends outwardly beyond the second edge of the first packaged microelectronic device.

66. (Previously presented) The assembly of claim 65 wherein the second packaged microelectronic device is spaced apart from the first packaged microelectronic device to define a gap between the packaged devices.

67. (Previously presented) The assembly of claim 65 wherein the support member includes support member circuitry, and further wherein all the elongated connection members of the second microelectronic device are attached directly to the support member circuitry.

68. (Cancelled)

69. (Previously presented) The assembly of claim 70, further comprising an elongated conductive connecting member connected between the second packaged microelectronic device and the support member circuitry, at least a portion of the connecting member being positioned adjacent to the first packaged microelectronic device.

70. (Previously presented) An assembly of packaged microelectronic devices, comprising:

- a support member having support member circuitry;

- a first packaged microelectronic device including a first microelectronic die electrically coupled directly to the support member circuitry, wherein the first packaged microelectronic device has a first edge and a second edge facing opposite the first edge; and

- a second packaged microelectronic device including a second microelectronic die electrically coupled directly to the support member circuitry without any direct electrical connections to the first packaged microelectronic device, the first packaged microelectronic device being positioned between the support member and the second packaged microelectronic device, the second packaged microelectronic device not being fixedly attached to the first packaged microelectronic device, the second packaged microelectronic device having a third edge and a fourth edge facing opposite the third edge, and wherein the third edge of the second packaged microelectronic device extends outwardly beyond the first edge of the first packaged microelectronic device and the fourth edge of the second packaged microelectronic device extends outwardly beyond the second edge of the first packaged microelectronic device.

71. (Previously presented) The assembly of claim 70 wherein the second packaged microelectronic device is spaced apart from the first packaged microelectronic device to define a gap between the packaged devices.

72. (Previously presented) The assembly of claim 70 wherein the first packaged microelectronic device is electrically coupled to the second packaged microelectronic device via the support member circuitry.

73. (Cancelled)

74. (Previously presented) The assembly of claim 76 wherein the second packaged microelectronic device is spaced apart from the first packaged microelectronic device to define a gap between the first and second packaged microelectronic devices.

75. (Withdrawn—Previously presented) The assembly of claim 76 wherein the second packaged microelectronic device engages the first packaged microelectronic device.

76. (Previously presented) An assembly of packaged microelectronic devices, comprising:

- a support member having support member circuitry;

- a first packaged microelectronic device including a first microelectronic die electrically coupled directly to the support member circuitry, wherein the first packaged microelectronic device has a first edge and a second edge facing opposite the first edge; and

- a second packaged microelectronic device including a second microelectronic die, the second packaged microelectronic device being connected directly to the support member with the first packaged microelectronic device being positioned between the support member and the second packaged microelectronic device, the second packaged microelectronic device not being fixedly attached to the first packaged microelectronic device, the second packaged microelectronic device having a third edge and a fourth edge facing opposite the third edge, and wherein the third edge of the second packaged microelectronic device extends outwardly beyond the first edge of the first packaged microelectronic device and the fourth edge of the

second packaged microelectronic device extends outwardly beyond the second edge of the first packaged microelectronic device.

77. (Previously presented) The assembly of claim 76 wherein the second packaged microelectronic device has a plurality of conductive members electrically coupled to the microelectronic substrate and extending away from an encapsulant of the second microelectronic device, further wherein all the conductive members extending away from the encapsulant of the second microelectronic device are attached directly between the second packaged microelectronic device and the support member circuitry.

78. (Withdrawn) An assembly of microelectronic devices, comprising:
a support member having support member circuitry;
a first microelectronic die at least partially encased in an encapsulant, attached to the support member, and coupled to the support member circuitry with first conductive members; and
an at least initially unpackaged second microelectronic die positioned at least proximate to the encapsulant of the first microelectronic die and coupled directly to the support member circuitry with second conductive members that are not connected to the first conductive members, with one of the first and second microelectronic dies being positioned between the support member and the other of the first and second microelectronic dies.

79. (Withdrawn) The assembly of claim 78 wherein the encapsulant is a first encapsulant, and wherein the assembly further comprises a second encapsulant disposed adjacent to the second microelectronic die after the second microelectronic die is coupled to the circuitry of the support member.

80. (Withdrawn) The assembly of claim 78 wherein the second microelectronic die engages the encapsulant of the first microelectronic die.

81. (Withdrawn) The assembly of claim 78 wherein the second microelectronic die is spaced apart from the encapsulant of the first microelectronic die.

82. (Withdrawn) The assembly of claim 78 wherein the first microelectronic die and the encapsulant are positioned between the support member and the second microelectronic die.

83. (Withdrawn) The assembly of claim 78 wherein the first conductive members include solder balls and the second conductive members include elongated conductive pins.

84. (New) An assembly of packaged microelectronic devices, comprising:
a support member;
a first packaged microelectronic device connected to the support member and having a first microelectronic die generally encased in a first encapsulant to define a first planform shape; and
a second packaged microelectronic device connected to the support member with the first packaged microelectronic device positioned between the support member and the second packaged microelectronic device, the second packaged microelectronic device having a second microelectronic die generally encased in a second encapsulant to define a second planform shape different than the first planform shape, wherein the second packaged microelectronic device is spaced apart from the first packaged microelectronic device to define a gap between the packaged devices.

85. (New) An assembly of packaged microelectronic devices, comprising:
a support member;
a first packaged microelectronic device connected to the support member and having a first microelectronic die generally encased in a first encapsulant to define a first device footprint; and
a second packaged microelectronic device connected to the support member with the first packaged microelectronic device positioned between the support member and the

second packaged microelectronic device, the second packaged microelectronic device having a second microelectronic die generally encased in a second encapsulant to define a second device footprint different than the first device footprint.